



185HR

High-Tg, Low-CTE Materials with High Thermal Reliability

185HR laminate and prepreg materials are a proprietary, high-performance resin system with a Tg of 180°C for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required.

185HR laminate and prepreg materials are manufactured using Isola's patented technology, reinforced with electrical grade (E-glass) glass fabric. This system delivers a 340°C decomposition temperature, a lower Z-axis expansion and offers lower loss compared to competitive products in this space. The 185HR system is also laser fluorescing and UV blocking for maximum compatibility with Automated Optical Inspection (AOI) systems, optical positioning systems and photoimageable solder mask imaging.

Product Attributes

High Thermal Reliability

Typical Market Applications

Automotive & Transportation , Medical, Industrial & Instrumentation , Aerospace & Defense , Consumer Electronics , Networking & Communication Systems

High Thermal Reliability

Data Sheet

Tg 180°C

Td 340°C

Dk 4.01

Df 0.0200

IPC-4101/98 /99 /101 /126

UL - File Number E41625

Last Updated December 7, 2017
Revision No: 14

Product Features

Product Availability

185HR Typical Values

Last Updated Dec 7, 2017

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Test data generated from rigid laminate	Resin Content	50	%	2.3.16.2
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Glass Transition Temperature (Tg) by DMA		185	°C	2.4.24.4
Decomposition Temperature (Td) by TGA @ 5% weight loss		340	°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260	60	Minutes	2.4.24.1
	B. T288	>15		
Z-Axis CTE	A. Pre-Tg	40	ppm/°C	2.4.24C
	B. Post-Tg	220	ppm/°C	
	C. 50 to 260°C, (Total Expansion)	2.7	%	
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/mK	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched	Pass	Pass Visual	2.4.13.1
	B. Etched			
Dk, Permittivity	A. @ 100 MHz	4.13	—	2.5.5.3 Bereskin Stripline Bereskin Stripline Bereskin Stripline Bereskin Stripline
	B. @ 1 GHz	4.04		
	C. @ 2 GHz	4.01		
	D. @ 5 GHz	3.88		
	E. @ 10 GHz	3.88		
Df, Loss Tangent	A. @ 100 MHz	0.0158	—	2.5.5.3 Bereskin Stripline Bereskin Stripline Bereskin Stripline Bereskin Stripline
	B. @ 1 GHz	0.0192		
	C. @ 2 GHz	0.0200		
	D. @ 5 GHz	0.0235		
	E. @ 10 GHz	0.0236		
Volume Resistivity	A. C-96/35/90	—	MΩ-cm	2.5.17.1
	B. After moisture resistance	3.0×10^8		
	C. At elevated temperature	7.0×10^8		
Surface Resistivity	A. C-96/35/90	—	MΩ	2.5.17.1
	B. After moisture resistance	3.0×10^6		
	C. At elevated temperature	2.0×10^8		
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		115	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		54 (1350)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile copper foil all copper foil >17 μm [0.669 mil] B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions	0.969 (5.5)	N/mm (lb/inch)	2.4.8C
		1.06 (5.9)		2.4.8.2A
		1.06 (5.9)		2.4.8.3
		0.969 (5.5)		2.4.8.3
Flexural Strength	A. Length direction	97,100	ksi	2.4.4B
	B. Cross direction	54,100		
Tensile Strength	A. Length direction	53,337	ksi	ASTM D3039
	B. Cross direction	35,678		
Young's Modulus	A. Length direction	3770	ksi	ASTM D790-15e2
	B. Cross direction	3337		
Poisson's Ratio	A. Length direction	0.172	—	ASTM D3039
	B. Cross direction	0.155		
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
Max Operating Temperature		130	°C	UL 796

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

